



RF360
Europe GmbH

Data sheet

SAW duplexer
LTE band 28

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Ordering code:	B39781B1250P810
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1 Application

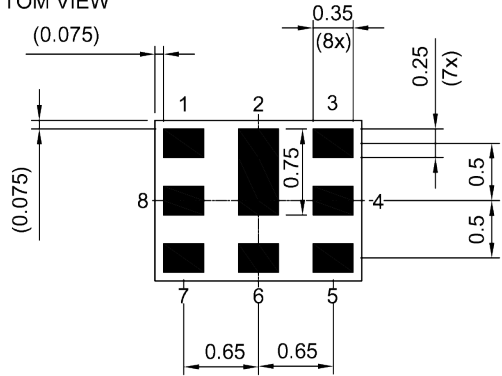
- Low-loss SAW duplexer for mobile telephone LTE Band 28 systems
- Usable pass band 45 MHz
- Single-ended duplexer

2 Features

- Package size $1.8_{\pm 0.1}$ mm \times $1.4_{\pm 0.1}$ mm
- Package height 0.475 mm (max.)
- Approximate weight 5 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

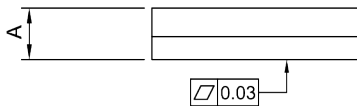
3 Package

BOTTOM VIEW

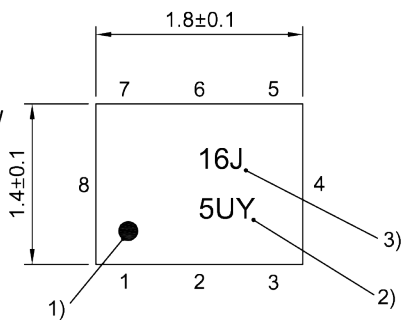


Pad and pitch tolerance ± 0.05

SIDE VIEW

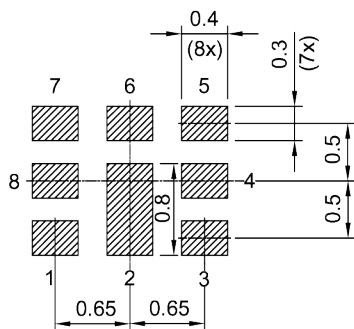


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

Figure 1: Drawing of package with package height A = 0.475 mm (max.). See Sec. Package information (p. 25).

4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 8 Ground

5 Matching circuit

- $L_{p6} = 13 \text{ nH}$

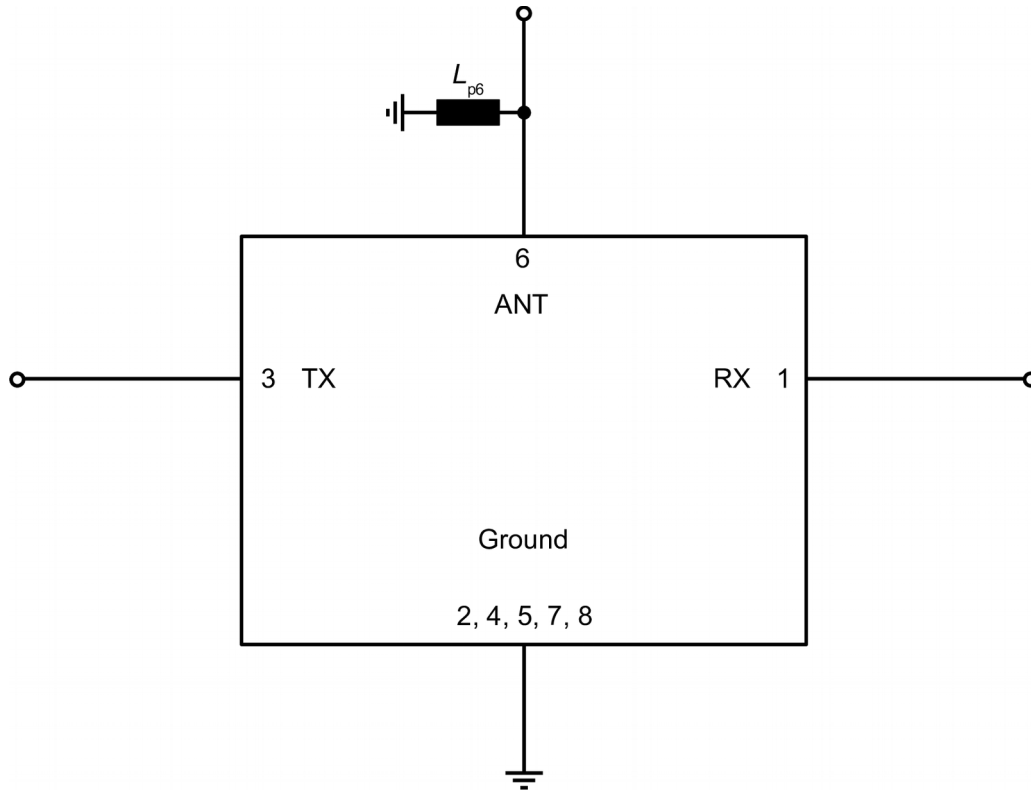


Figure 2: Schematic of matching circuit.

External shunt inductor for ESD protection is recommended at any ports towards antenna.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= -30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 13 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	725.5	—	MHz
Maximum insertion attenuation			$\alpha_{INT,max}^{2)}$				
	703... 748	MHz		—	1.6	2.0 ³⁾	dB
	703... 748	MHz		—	1.6	2.4	dB
Amplitude ripple (p-p)			$\Delta\alpha_{INT}^{2)}$				
	703... 748	MHz		—	0.8	1.7	dB
Maximum VSWR			VSWR _{max}				
@ TX port	703.24... 747.76	MHz		—	1.4	2.0	
@ ANT port	703.24... 747.76	MHz		—	1.4	2.0	
Average attenuation			α_{avg}				
	470... 694	MHz		30 ⁴⁾	33 ⁴⁾	—	dB
	692... 698	MHz		18 ^{3),5)}	23 ⁵⁾	—	dB
Minimum attenuation			α_{min}				
	10... 470	MHz		30	41	—	dB
	758... 803	MHz	$\alpha_{INT,min}^{2)}$	48	59	—	dB
	859... 894	MHz	α_{min}	37	42	—	dB
	1225... 1250	MHz	α_{min}	34	40	—	dB
	1406... 1510	MHz	α_{min}	35	38	—	dB
	1559... 1563	MHz	α_{min}	32	36	—	dB
	1565.42... 1573.374	MHz	α_{min}	32	35	—	dB
	1573.374... 1577.466	MHz	α_{min}	32	35	—	dB
	1577.466... 1585.42	MHz	α_{min}	32	35	—	dB
	1597.5515... 1605.886	MHz	α_{min}	31	35	—	dB
	1805... 1880	MHz	α_{min}	27	31	—	dB
	1930... 1995	MHz	α_{min}	27	31	—	dB
	2010... 2025	MHz	α_{min}	27	31	—	dB
	2109... 2244	MHz	α_{min}	27	30	—	dB
	2400... 2484	MHz	α_{min}	25	29	—	dB
	2570... 2620	MHz	α_{min}	25	29	—	dB
	2812... 2992	MHz	α_{min}	24	29	—	dB
	4900... 5950	MHz	α_{min}	5	8	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

- ³⁾ Valid for typical temperature $T = +25\text{ °C}$.
- ⁴⁾ Over any channel with band width of 8MHz.
- ⁵⁾ Over any channel with band width of 6MHz.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= -30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 13 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	780.5	—	MHz
Maximum insertion attenuation			$\alpha_{INT,max}^{2)}$				
	758... 803	MHz		—	1.8	2.1 ³⁾	dB
	758... 803	MHz		—	1.8	2.6	dB
Amplitude ripple (p-p)			$\Delta\alpha_{INT}^{2)}$				
	758... 803	MHz		—	1.0	1.8	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	758.24... 802.76	MHz		—	1.5	2.0	
@ RX port	758.24... 802.76	MHz		—	1.4	2.0	
Minimum attenuation							
	10... 699	MHz	α_{min}	35	41	—	dB
	45... 65	MHz	α_{min}	50	65	—	dB
	703... 748	MHz	$\alpha_{INT,min}^{2)}$	50	53	—	dB
	814... 834	MHz	α_{min}	5	10	—	dB
	834... 900	MHz	α_{min}	40	48	—	dB
	900... 3000	MHz	α_{min}	34	39	—	dB
	3000... 6000	MHz	α_{min}	20	25	—	dB

1) See Sec. Matching circuit (p. 6).
 2) Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
 3) Valid for typical temperature $T = +25$ °C.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= -30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 13 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Minimum isolation	$\alpha_{INT,min}$ ²⁾	703... 748 MHz	52	55	—	dB
		758... 803 MHz	55	62	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

7 Maximum ratings

Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
ESD voltage		
	$V_{ESD}^{3)} = 150\text{ V (max.)}$	Machine model.
	$V_{ESD}^{4)} = 325\text{ V (max.)}$	Human body model.
	$V_{ESD}^{5)} = 700\text{ V (max.)}$	Charged device model.
Input power	P_{IN}	
@ TX port: 703 ... 748 MHz	29 dBm (max.)	Continuous wave for 5000 h @ 50 °C.
@ TX port: other frequency ranges	10 dBm (max.)	Continuous wave for 5000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁵⁾ According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

8 Transmission coefficients

8.1 TX – ANT

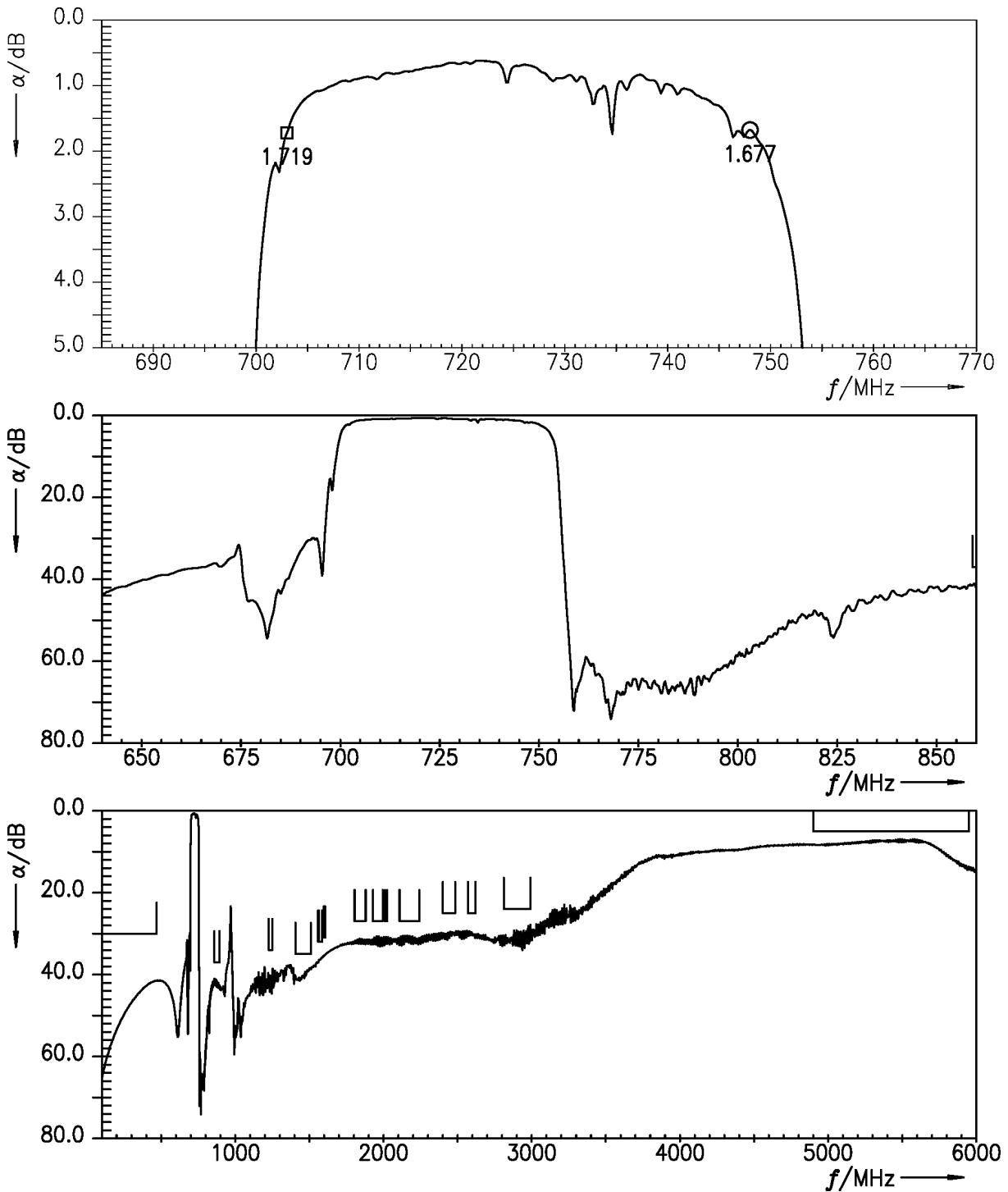


Figure 3: Attenuation TX – ANT.

8.2 ANT – RX

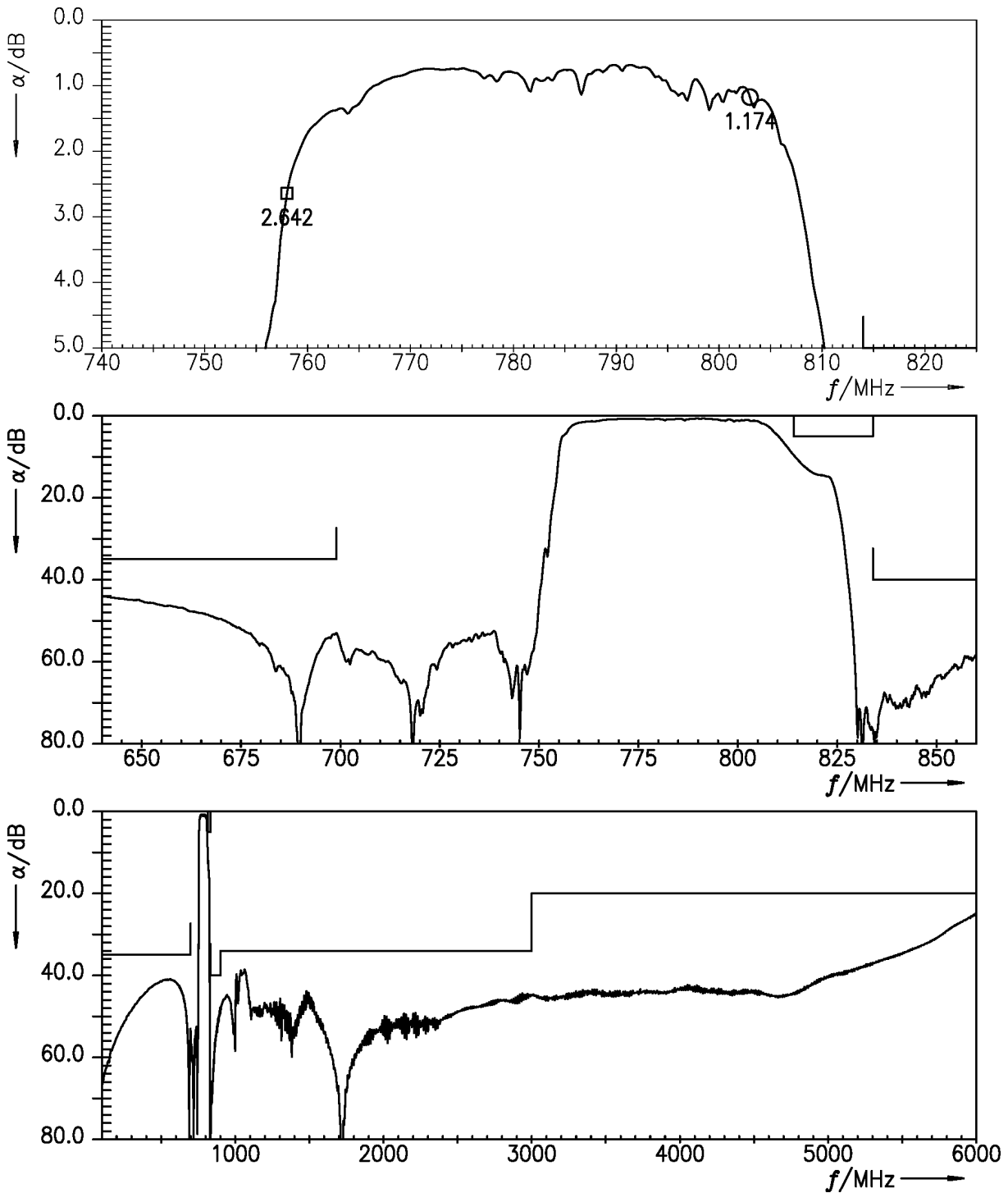


Figure 4: Attenuation ANT – RX.

9 Transmission coefficients (LTE)

9.1 TX – ANT

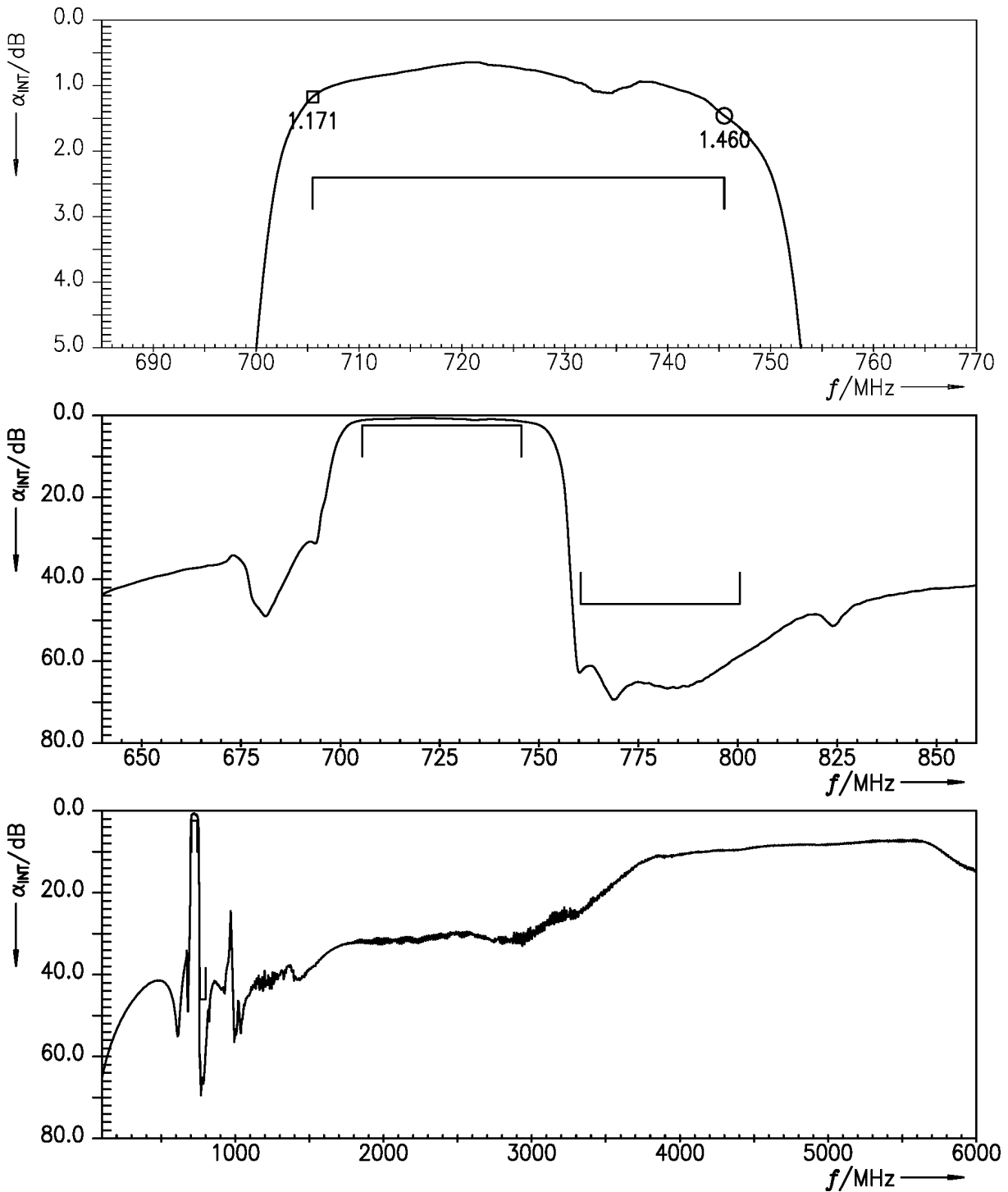


Figure 5: Attenuation (LTE) (integration window = 5 MHz) TX – ANT.

9.2 ANT – RX

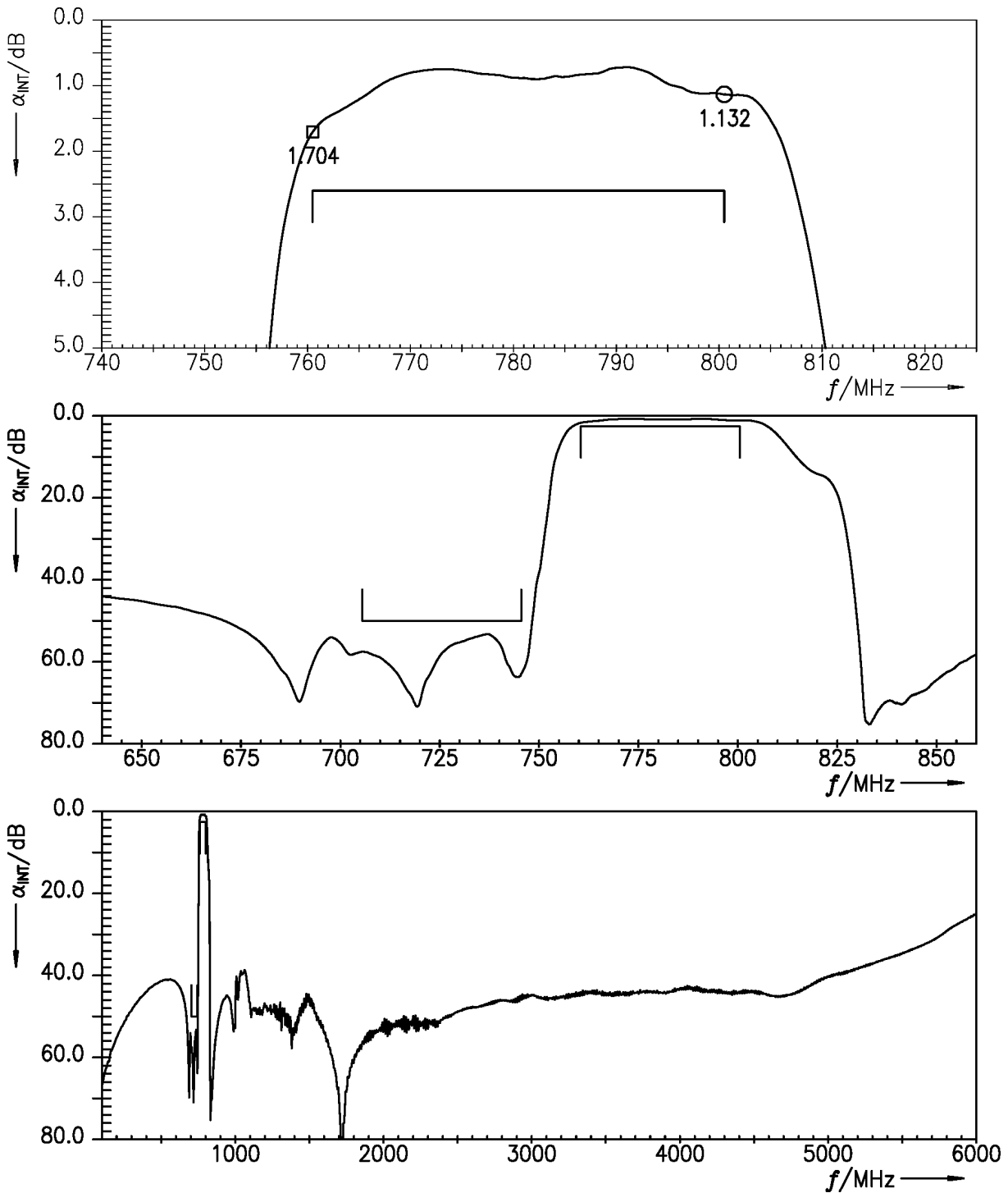


Figure 6: Attenuation (LTE) (integration window = 5 MHz) ANT – RX.

9.3 TX – RX

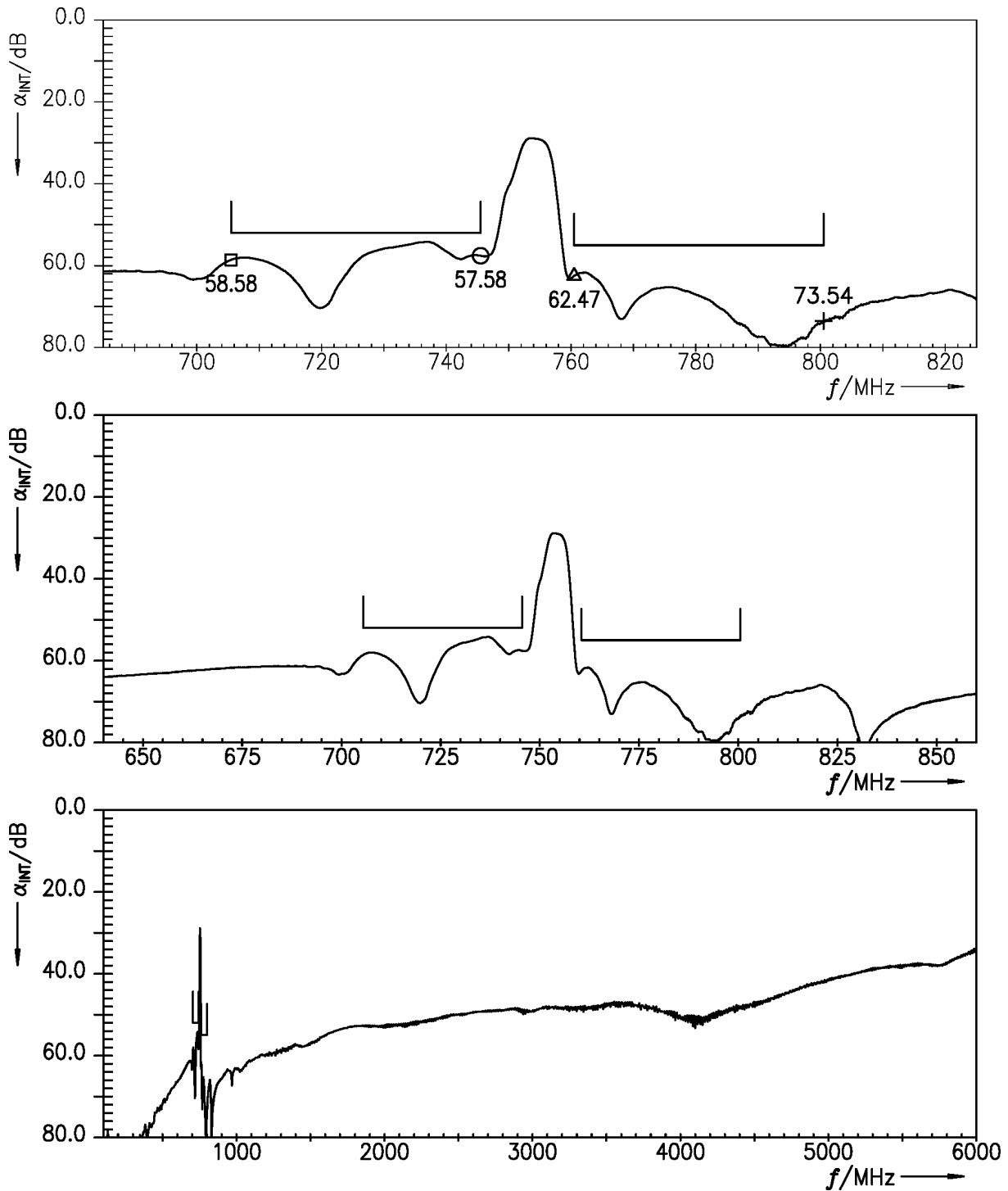


Figure 7: Isolation (LTE) (integration window = 5 MHz) TX – RX.

10 Reflection coefficients

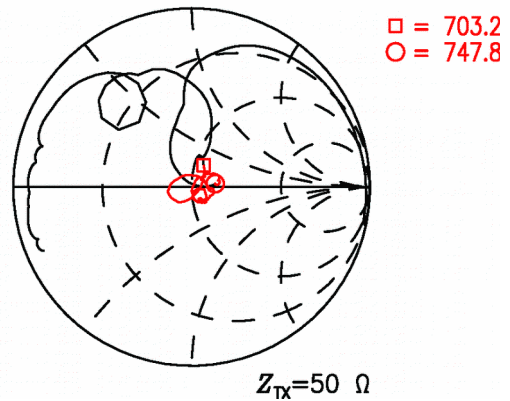
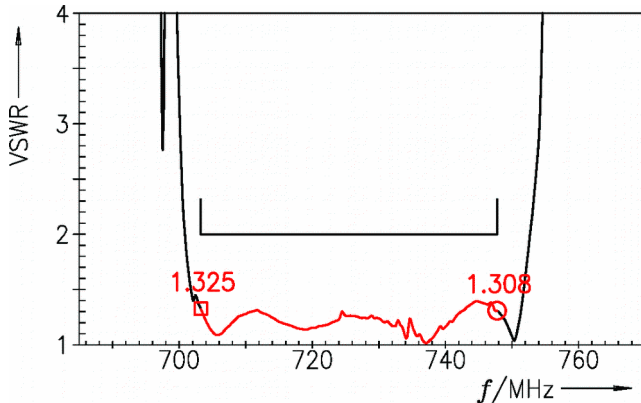


Figure 8: Reflection coefficient at TX port.

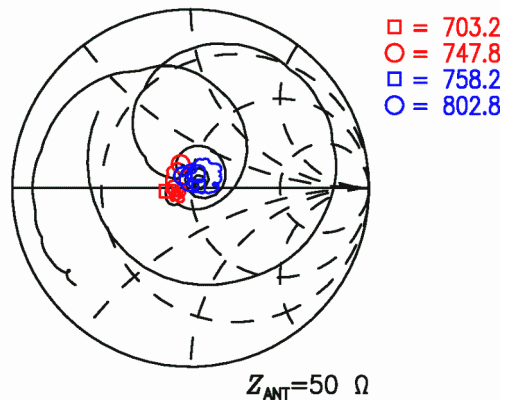
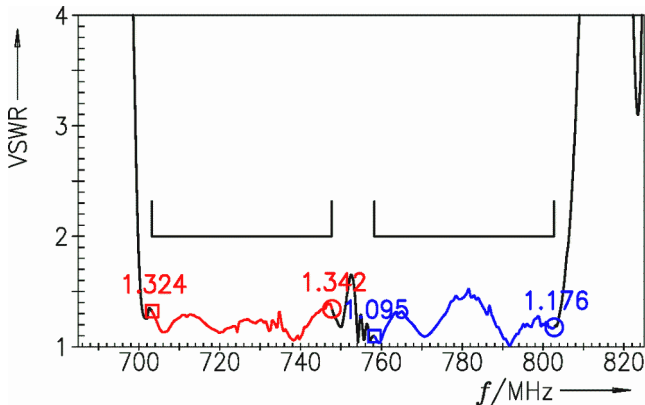


Figure 9: Reflection coefficient at ANT port.

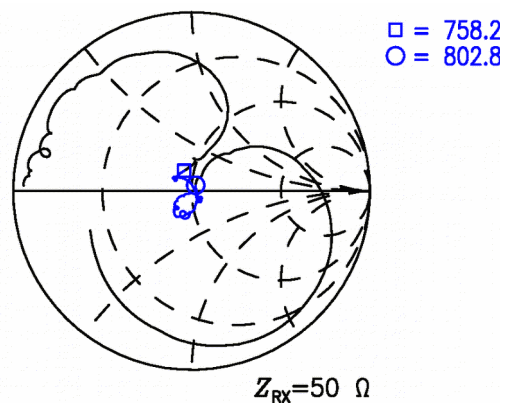
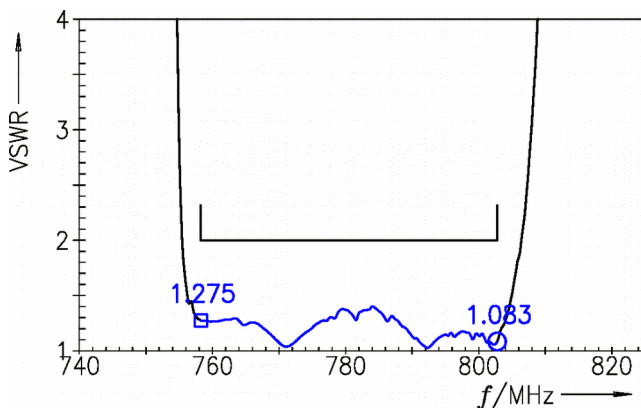


Figure 10: Reflection coefficient at RX port.

11 Packing material

11.1 Tape

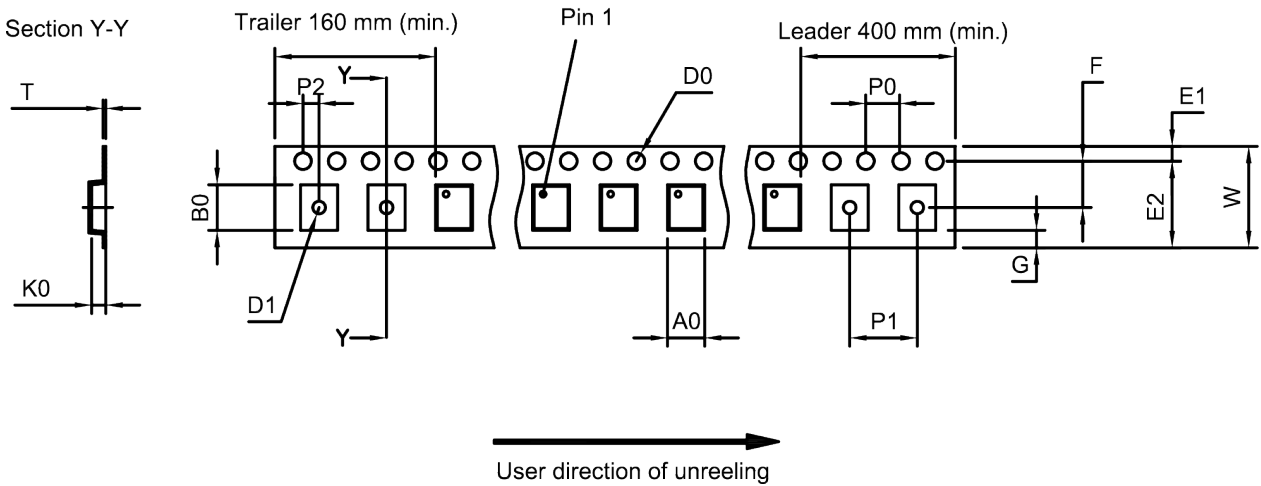


Figure 11: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.6±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	2.0±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	0.8+0.1/-0 mm	K ₀	0.64±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

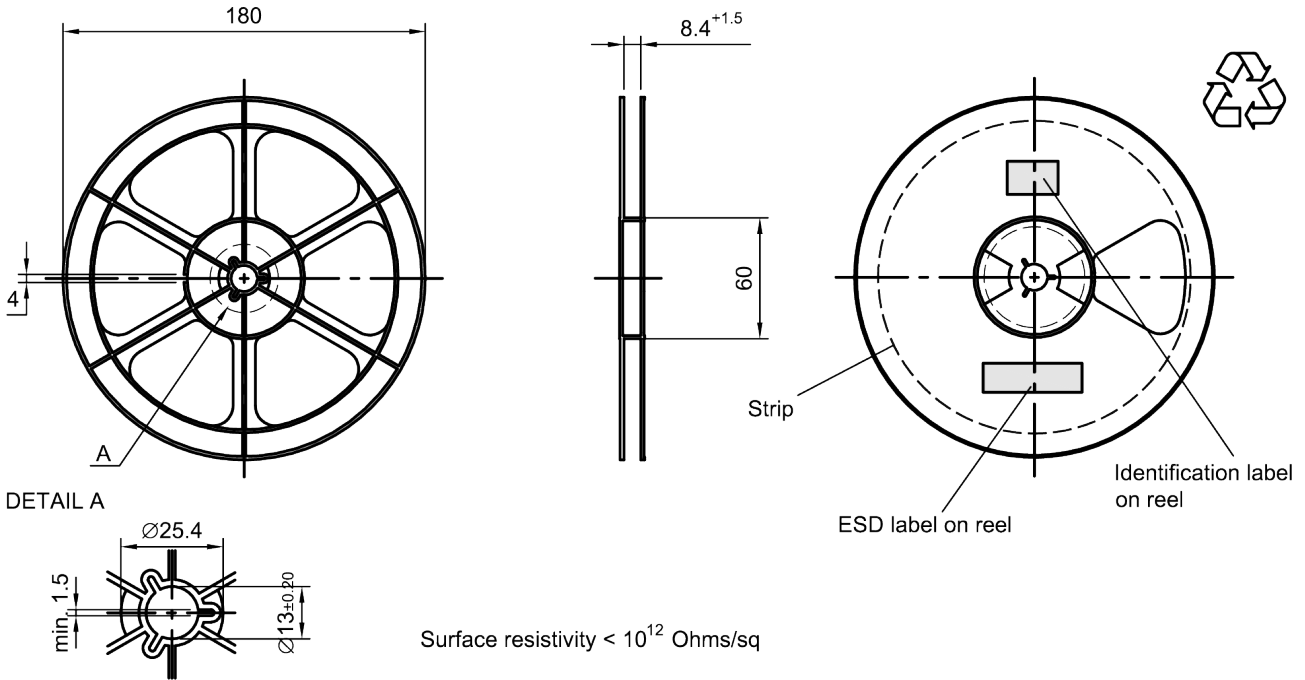


Figure 12: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

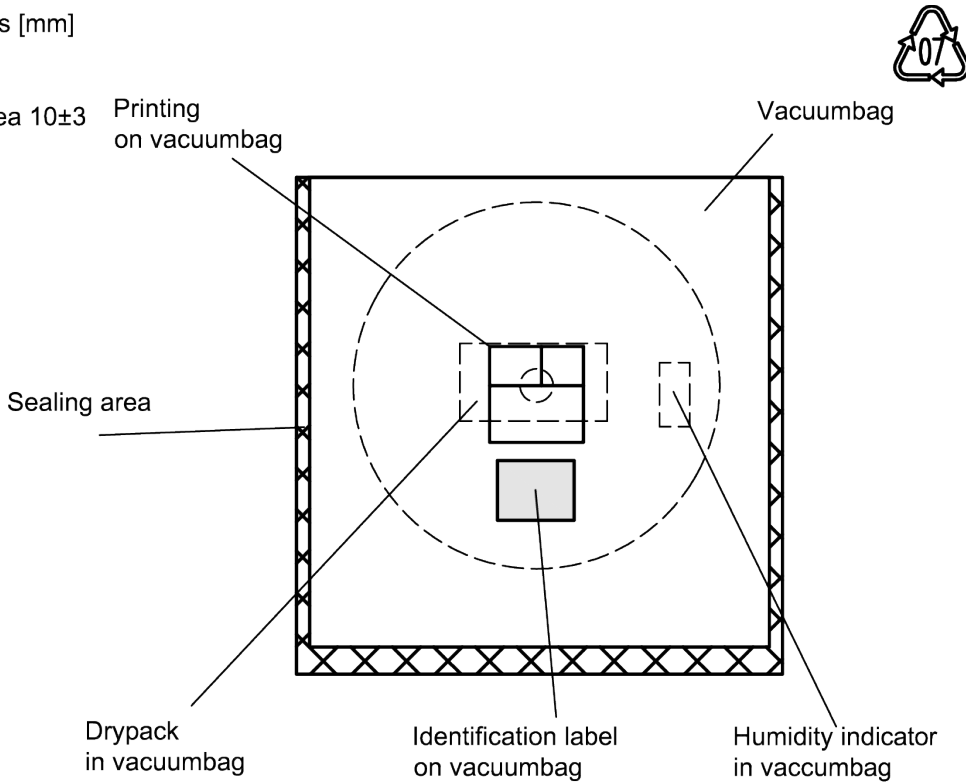


Figure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Dimensions [mm]
L = 188
B = 188
H = 30
Tolerance ± 5

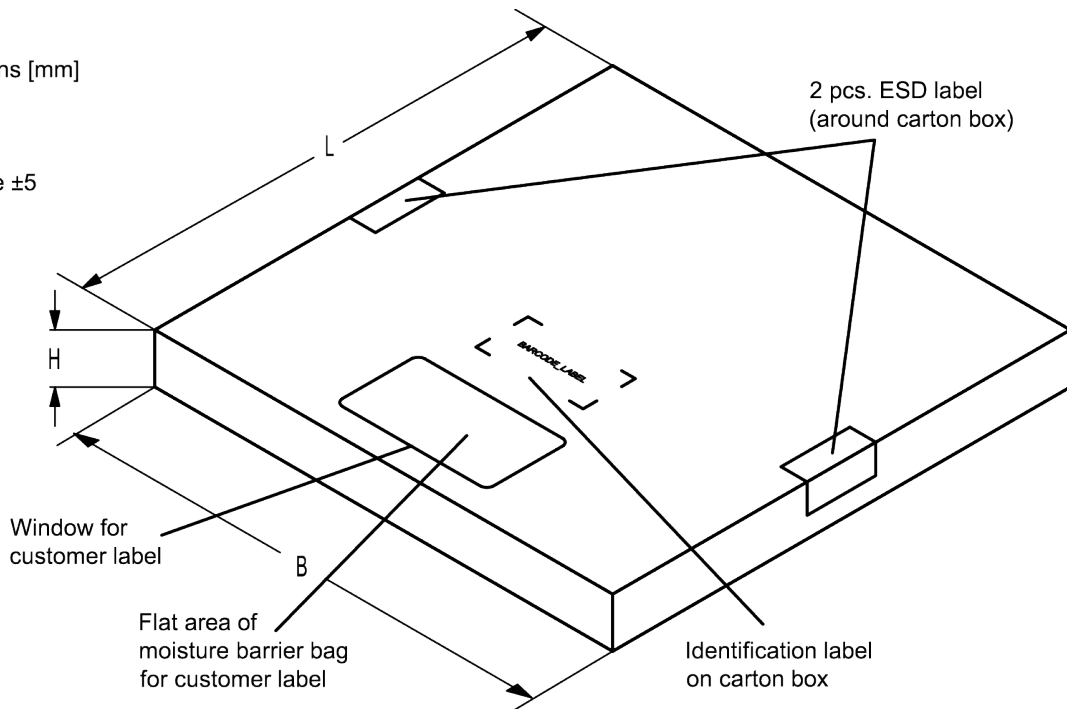


Figure 14: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

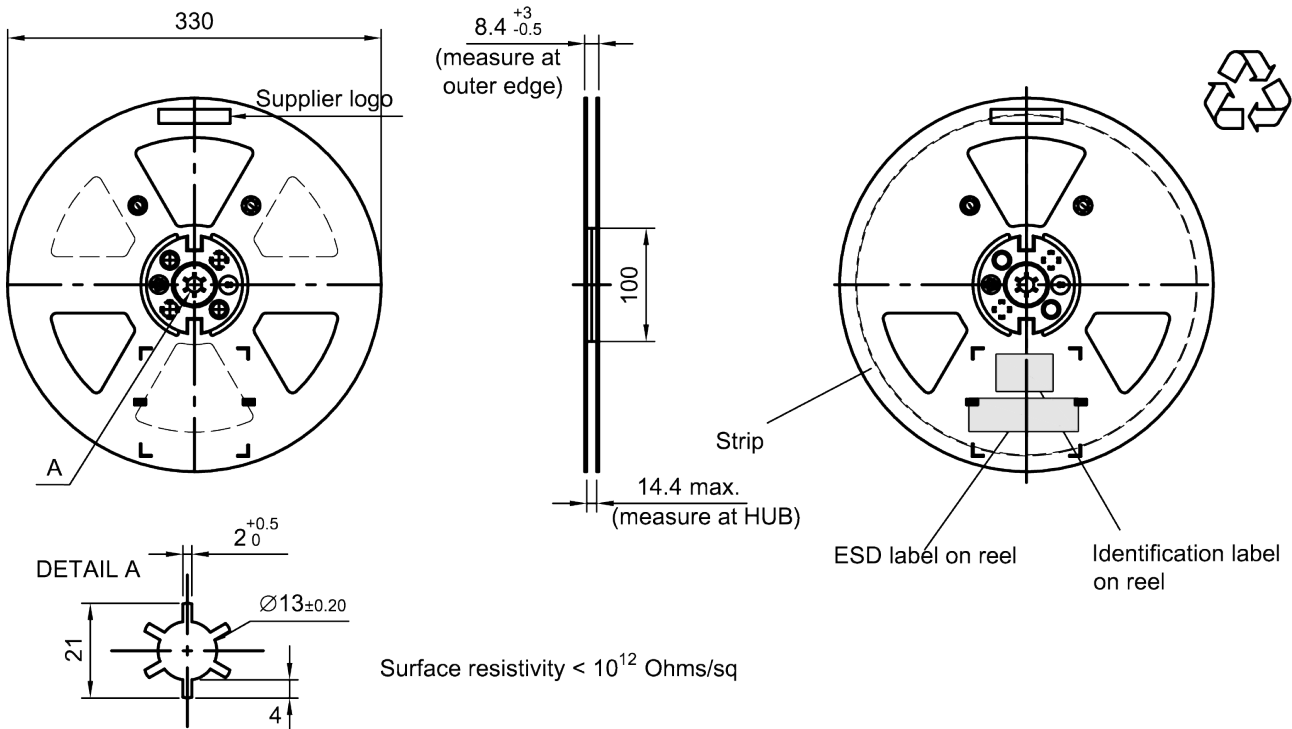


Figure 15: Drawing of reel (first-angle projection) with diameter of 330 mm.

Dimensions [mm]

X = 400+5

Y = 418+5

Sealing area 10±3

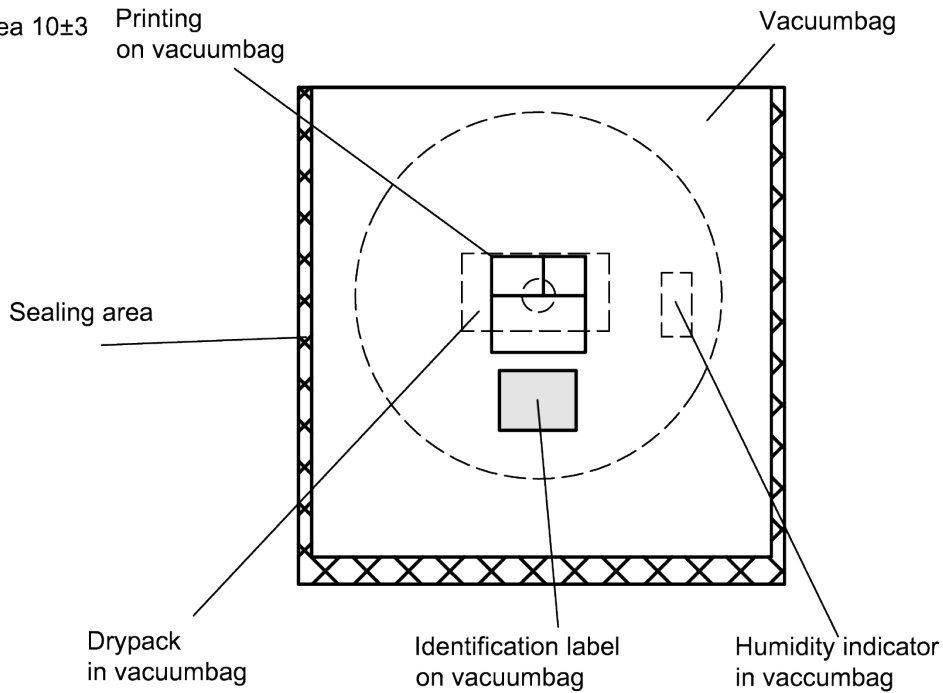


Figure 16: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

Dimensions [mm]

L = 335

B = 338

H = 36 (for 8 mm tape width)

40 (for 12 mm tape width)

Tolerance ±5

2 pcs. ESD label
(around carton box)

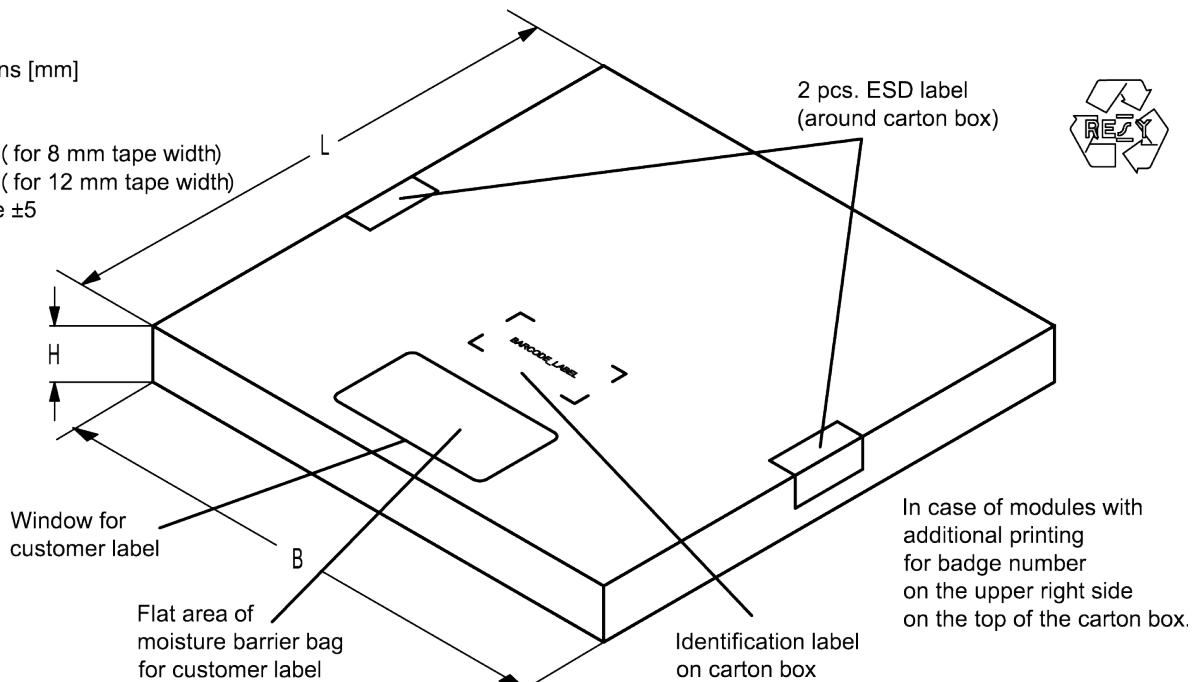


Figure 17: Drawing of folding box for reel with diameter of 330 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.
16J => **1234**
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$ **1234**
 The BASE32 code for product type B1250 is 172.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.
5UY => **12345**
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

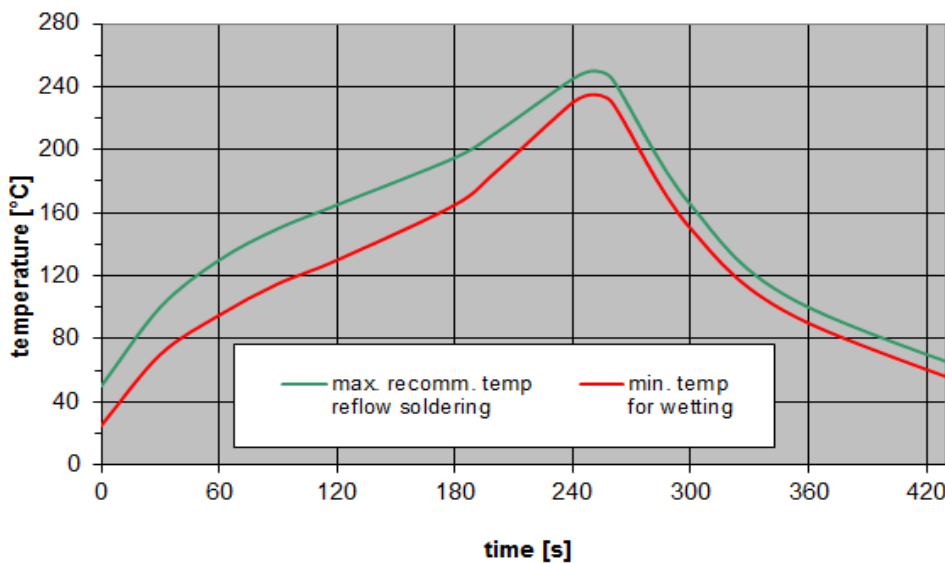


Figure 18: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

Ordering code	Packing unit
B39781B1250P810	15000 pcs
B39781B1250P810S 5	5000 pcs

Table 4: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rfe.qualcomm.com/>.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (<https://rfe.qualcomm.com>). Should you have any more detailed questions, please contact our sales offices.
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